

1/4

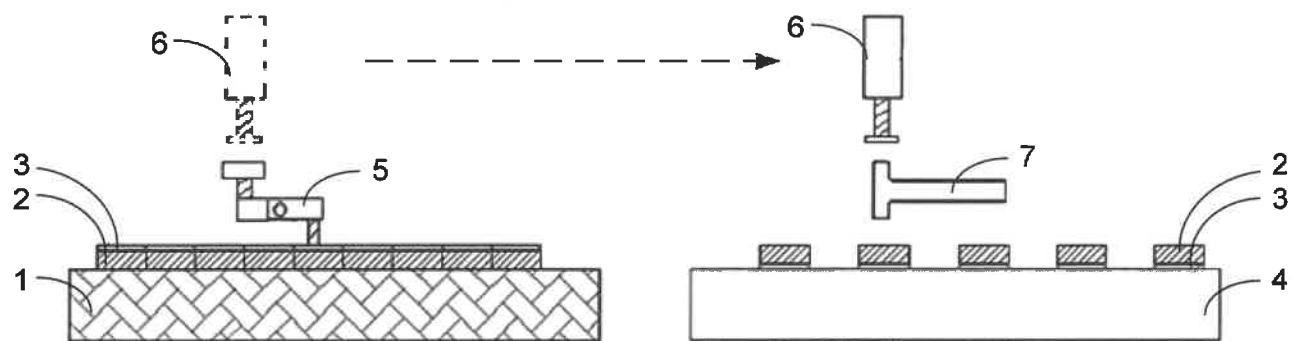


Fig. 1

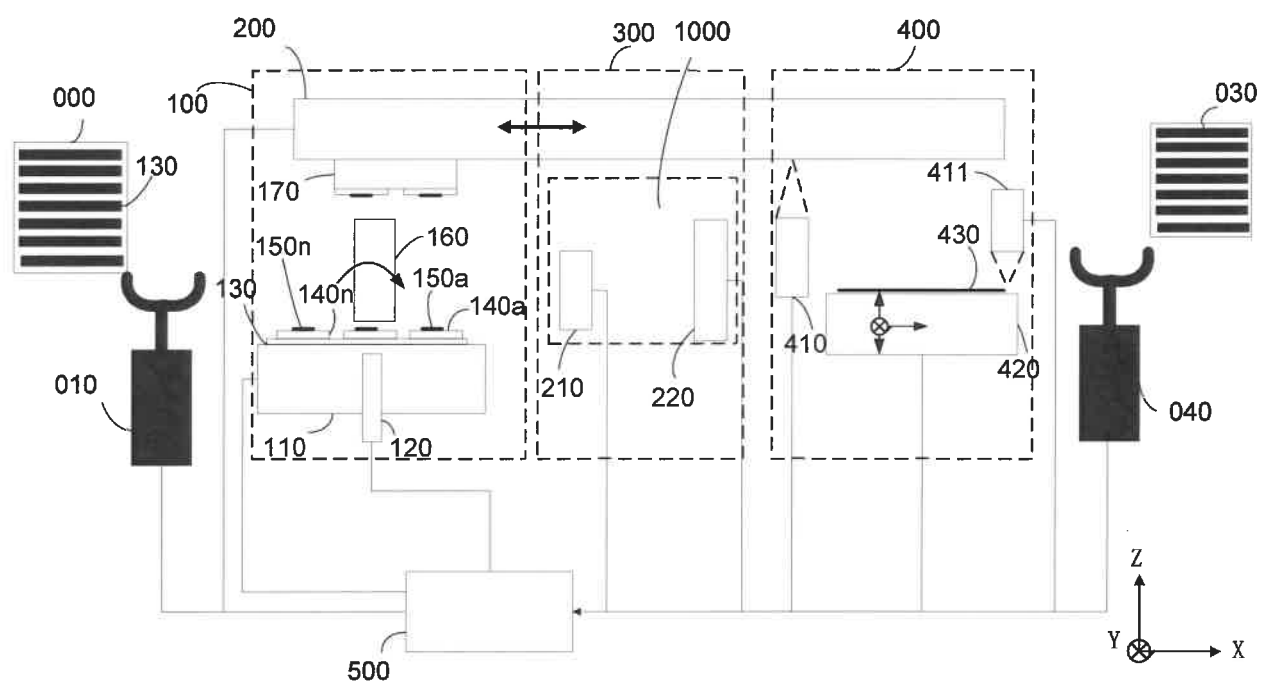


Fig. 2

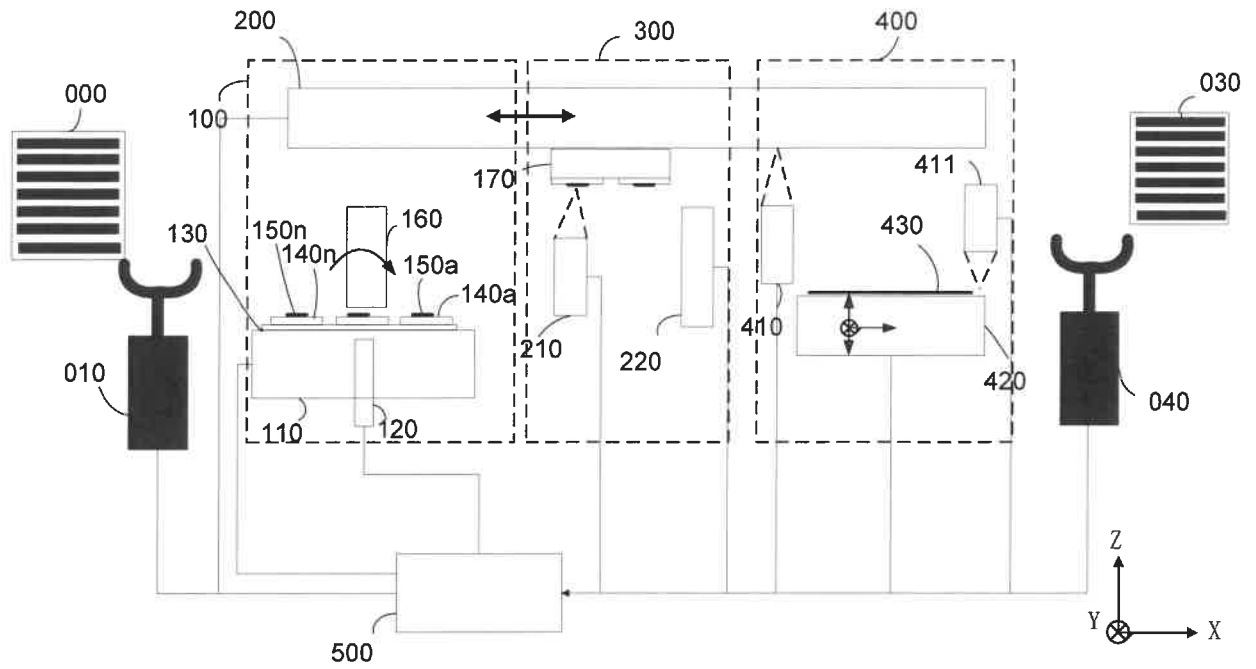


Fig. 3

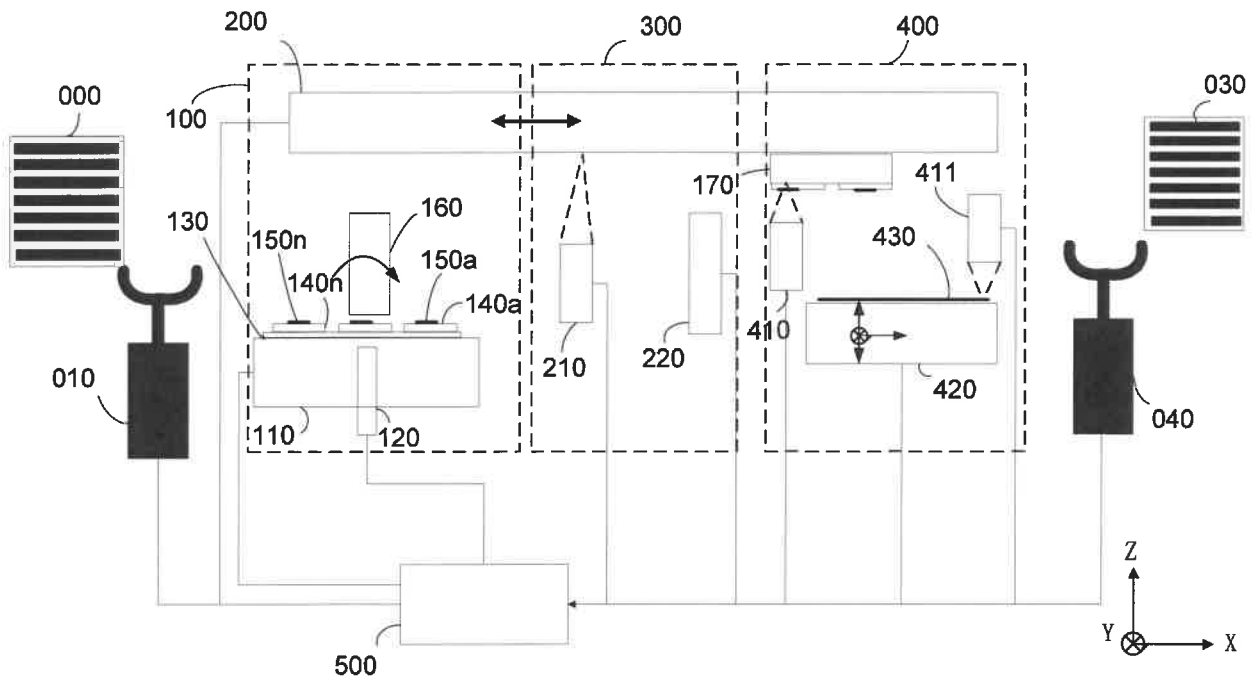


Fig. 4

160

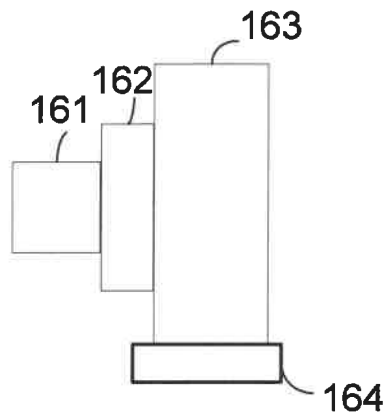


Fig. 5

120

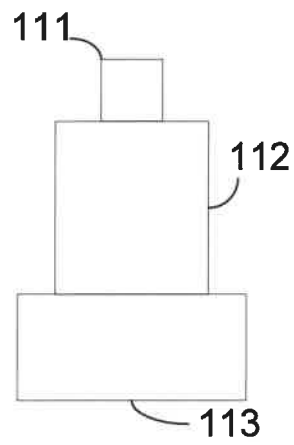


Fig. 6

220

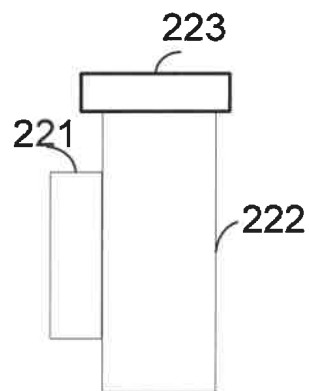
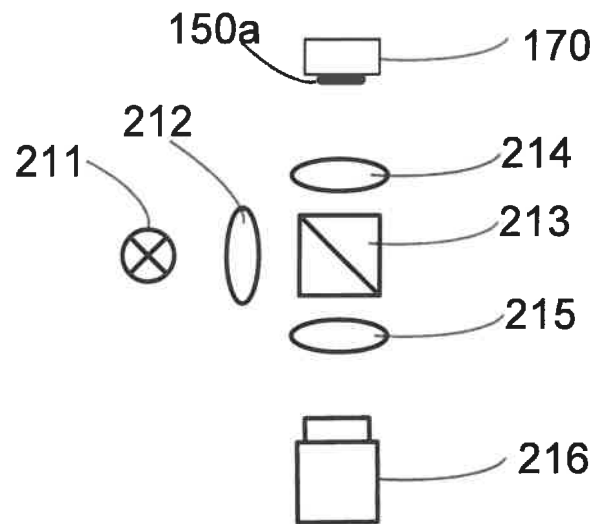


Fig. 7

**Fig. 8**

The first motion stage transports a set of chips to the chip pickup means and the second motion stage moves the transfer carrier to the chip pickup means

The chip pickup means pick up the chips from the first motion stage and cause their temporary retention on the transfer carrier

The second motion stage transports the transfer carrier on which the chips are temporarily retained to the chip adjustment system

The chip adjustment system adjusts the positions of the chips on the transfer carrier

The second motion stage transports the transfer carrier retaining the position-adjusted chips to a substrate

The bonding stage that supports the substrate causes final bonding of the substrate to the chips on the transfer carrier

Fig. 9